

(19) World Intellectual Property Organization
International Bureau



(43) International Publication Date
13 June 2002 (13.06.2002)

PCT

(10) International Publication Number
WO 02/047162 A3

(51) International Patent Classification⁷: **H01L 23/433**,
23/538

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(21) International Application Number: PCT/US01/49898

(22) International Filing Date:
9 November 2001 (09.11.2001)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
09/733,289 8 December 2000 (08.12.2000) US

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(81) Designated States (*national*): AE, AG, AL, AM, AT, AU,
AZ, BA, BB, BG, BR, BY, BZ, CA, CH, CN, CO, CR, CU,
CZ, DE, DK, DM, DZ, EC, EE, ES, FI, GB, GD, GE, GH,
GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC,
LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW,
MX, MZ, NO, NZ, PH, PL, PT, RO, RU, SD, SE, SG, SI,
SK, SL, TJ, TM, TR, TT, TZ, UA, UG, US, UZ, VN, YU,
ZA, ZW.

(84) Designated States (*regional*): ARIPO patent (GH, GM,
KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZW), Eurasian
patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European
patent (AT, BE, CH, CY, DE, DK, ES, FI, FR, GB, GR, IE,
IT, LU, MC, NL, PT, SE, TR), OAPI patent (BF, BJ, CF,
CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD,
TG).

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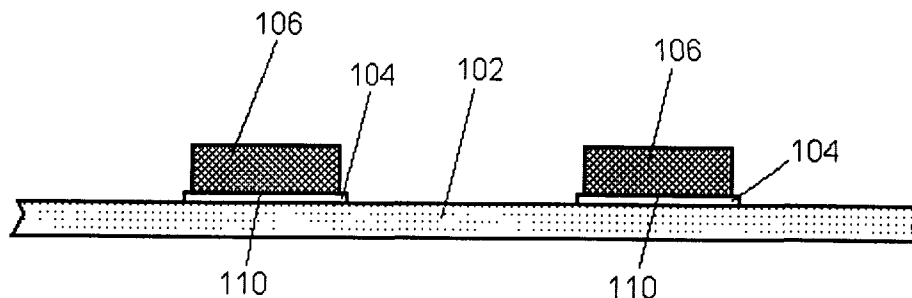
Published:

— with international search report

(88) Date of publication of the international search report:
7 August 2003

*For two-letter codes and other abbreviations, refer to the "Guid-
ance Notes on Codes and Abbreviations" appearing at the begin-
ning of each regular issue of the PCT Gazette.*

(54) Title: MICROELECTRONIC PACKAGE HAVING AN INTEGRATED HEAT SINK AND BUILD-UP LAYERS



(57) Abstract: A microelectronic package fabrication technology that attaches at least one microelectronic die onto a heat spreader and encapsulates the microelectronic die/dice thereon which may further include a microelectronic packaging core abutting the heat spreader wherein the microelectronic die/dice reside within at least one opening in a microelectronic package core. After encapsulation, build-up layers may be fabricated to form electrical connections with the microelectronic die/dice.



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